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2015年3月

## **FDMC86570LET60**

# N 沟道屏蔽栅极 PowerTrench<sup>®</sup> MOSFET 60 V, 87 A, 4.3 mΩ

#### 特性

- T」 额定值扩展: 175°C
- 屏蔽栅极 MOSFET 技术
- 最大  $r_{DS(on)}$  = 4.3 m $\Omega$  ( $V_{GS}$  = 10 V,  $I_D$  = 18 A)
- 最大  $r_{DS(on)}$  = 6.5 m $\Omega$  ( $V_{GS}$  = 4.5 V,  $I_D$  = 15 A)
- 高性能沟道技术可实现极低的 r<sub>DS(on)</sub>
- 终端为无铅产品
- 符合 RoHS 标准



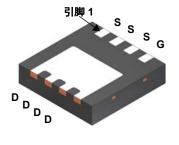
#### 概述

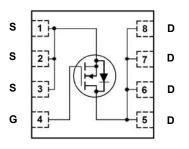
此 N 沟道 MOSFET 采用飞兆带屏蔽栅极技术的先进 PowerTrench<sup>®</sup> 工艺生产。该工艺针对导通阻抗优化,可保持卓越开关性能。

#### 应用

■ DC-DC 转换







Power 33

### MOSFET 最大额定值 T<sub>A</sub> = 25 ℃ 除非另有说明。

符号		参数		额定值	单位
$V_{DS}$	漏极一源极电压			60	V
$V_{GS}$	栅极一源极电压			±20	V
	漏极电流 - 连续	T <sub>C</sub> = 25 °C	(注5)	87	
I-	- 连续	T <sub>C</sub> = 100 °C	(注 5)	62	A
ID	- 连续	T <sub>A</sub> = 25 °C	(注 1a)	18	
	- 脉冲		(注4)	436	
E <sub>AS</sub>	单脉冲雪崩能量		(注3)	253	mJ
P <sub>D</sub>	功耗	T <sub>C</sub> = 25 °C		65	W
	功耗	T <sub>A</sub> = 25 °C	(注 1a)	2.8	VV
T <sub>J</sub> , T <sub>STG</sub>	工作和存储结温范围			-55 至 +175	°C

#### 热性能

$R_{\theta JC}$	结至外壳规阻 (	注 1)	2.3	°C/W
$R_{\theta JA}$	结至环境热阻(注		53	C/VV

#### 封装标识与定购信息

器件标识	器件	封装	卷尺寸	带宽	数量
FDMC86570LT	FDMC86570LET60	Power33	13 "	12 mm	3000 个

## 电气特性 T」= 25°C 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV <sub>DSS</sub>	漏极一源极击穿电压	$I_D = 250 \mu\text{A},  V_{GS} = 0 \text{V}$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	击穿电压温度系数	I <sub>D</sub> = 250 μA,参考 25 °C		30		mV/°C
I <sub>DSS</sub>	零栅极电压漏极电流	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	栅极一源极漏电流	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### 导通特性

$V_{GS(th)}$	栅极一源极阈值电压	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	栅极一源极阈值电压 温度系数	I <sub>D</sub> = 250 μA,参考 25 °C		-7		mV/°C
r <sub>DS(on)</sub>	漏极至源极静态导通电阻	$V_{GS} = 10 \text{ V}, I_D = 18 \text{ A}$		3.1	4.3	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		4.7	6.5	mΩ
		$V_{GS}$ = 10 V, $I_{D}$ = 18 A, $T_{J}$ = 125 °C		5.0	6.9	1
9 <sub>FS</sub>	正向跨导	V <sub>DD</sub> = 5 V, I <sub>D</sub> = 18 A		75		S

#### 动态特性

C <sub>iss</sub>	输入电容	V - 20 V V - 0 V		4790		pF
C <sub>oss</sub>	输出电容	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, f = 1 MHz		821		pF
C <sub>rss</sub>	反向传输电容	1 - 1 1011 12		19		pF
$R_g$	栅极阻抗		0.1	0.9	2.7	Ω

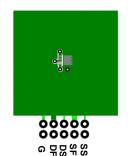
#### 开关特性

t <sub>d(on)</sub>	导通延迟时间		19	34	ns
t <sub>r</sub>	上升时间	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 18 A,	6.2	12	ns
t <sub>d(off)</sub>	关断延迟时间	$V_{GS}$ = 10 V, $R_{GEN}$ = 6 $\Omega$	38	61	ns
t <sub>f</sub>	下降时间		3.9	10	ns
$Q_{g(TOT)}$	总栅极电荷	V <sub>GS</sub> = 0 V 至 10 V	63	88	nC
$Q_{g(TOT)}$	总栅极电荷	V <sub>GS</sub> = 0 V 至 4.5 V V <sub>DD</sub> = 30 V,	29	41	nC
Q <sub>gs</sub>	栅极一源极电荷	I <sub>D</sub> = 18 A	14		nC
$Q_{gd}$	栅极一漏极"米勒"电荷		6.3		nC

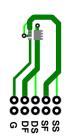
#### 漏极一源极二极管特性

V <sub>SD</sub>	源极一漏极二极管正向电压 $\frac{V_{GS} = 0 \text{ V},}{V_{GS} = 0 \text{ V},}$	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 18 A	(注2)	8.0	1.3	V
		$V_{GS} = 0 V, I_{S} = 1.9 A$	(注2)	0.7	1.2	V
t <sub>rr</sub>	反向恢复时间	I <sub>F</sub> = 18 A, di/dt = 100 A/μs		43	69	ns
Q <sub>rr</sub>	反向恢复电荷			26	42	nC

注意: 1.  $R_{\theta JA}$  取决于安装在一平方英寸衬垫, 2oz 铜焊盘以及 FR-4 材质尺寸 1.5 x 1.5in. 的衬垫上的器件。  $R_{\theta CA}$  由用户的电路板设计确定。



a. 53 安装在 2 oz 最小 1 in<sup>2</sup> 铜 焊盘上时的 °C/W



b. 125 安装在 2 oz 最小铜焊盘上 时的 °C/W

- 2. 脉冲测试:脉冲宽度:<300 μs,占空比:< 2.0%。
- 3. E\_AS 为 253 mJ,依据起始 T\_J = 25 °C、L = 3 mH、  $I_{AS}$  = 13 A、  $V_{DD}$  = 60 V、  $V_{GS}$  = 10 V。 100% 经过测试(L = 0.1 mH,  $I_{AS}$  = 43 A)。
- 4. 有关脉冲编号的更多详情,请参考图 11 中的 SOA 图形。
- 5. 计算得到的连续电流仅限于最大结温,实际连续电流将受限于散热以及电气机械应用的电路板设计。

### 典型特性 T」= 25℃ 除非另有说明

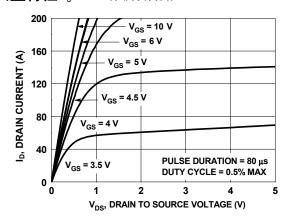


图 1. 通态区域特性

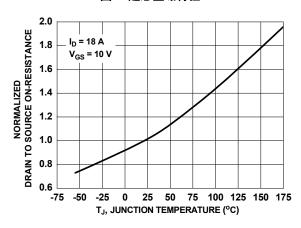


图 3. 标准化导通电阻与结温的关系

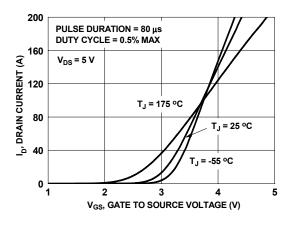


图 5. 转换特性

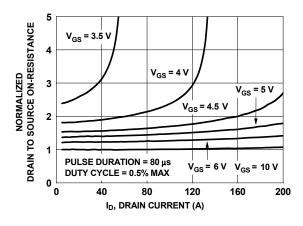


图 2. 标准化导通电阻与漏极电流和栅极电压的关系

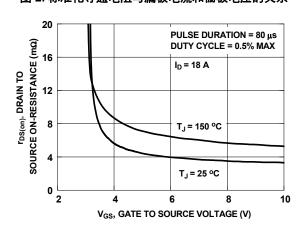


图 4. 导通电阻与栅极 - 源极电压的关系

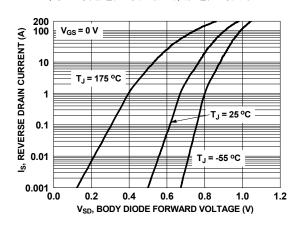


图 6. 源极 - 漏极二极管正向电压与源电流的关系

## 典型特性 T」 = 25℃ 除非另有说明

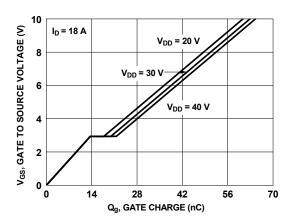


图 7. 栅极电荷特性

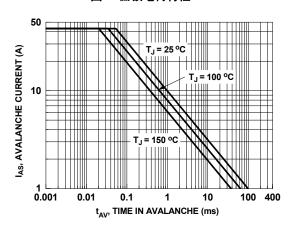


图 9. 非箝位电感开关能力

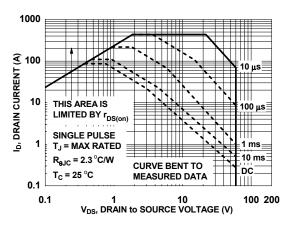


图 11. 正向偏压安全工作区

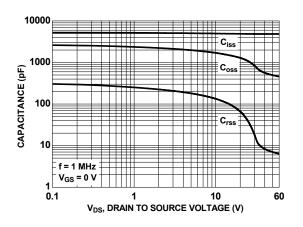


图 8. 电容与漏极 - 源极电压的关系

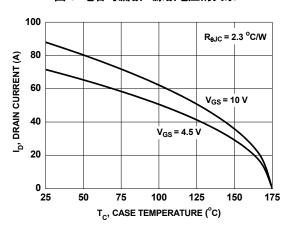


图 10. 最大连续漏极电流与壳温的关系

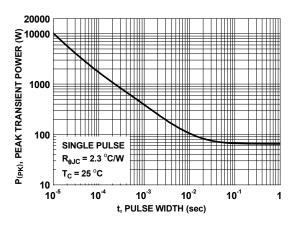


图 12. 单个脉冲最大功耗

## 典型特性 T」 = 25°C 除非另有说明

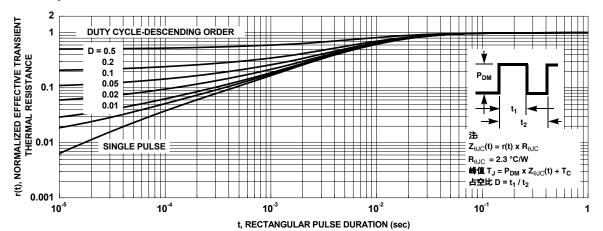
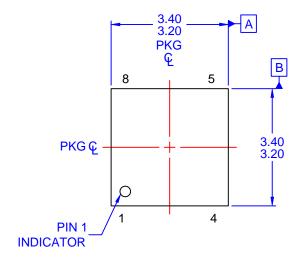
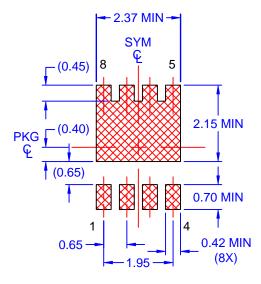


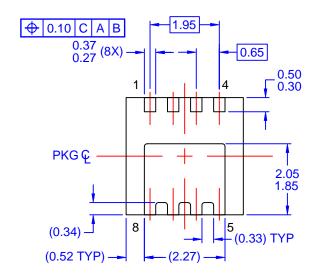
图 13. 结至外壳瞬态热响应曲线





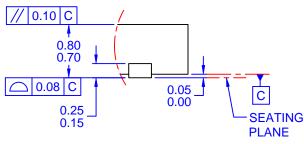


LAND PATTERN RECOMMENDATION



#### NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08HREV1



DETAIL A
SCALE: 2X

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